

Customer No.: 31561  
Application No.: 10710,621  
Docket No.: 11576-US-PA

### REMARKS

#### Present Status of Application

The Office Action dated October 05, 2004, has allowed claims 1-7. Claims 8-10 and 12-13 were rejected under 35 USC§102(e) as being anticipated by Chen et al. (US Patent No. 6,602,775). Claims 11 and 14 were rejected under 35 USC§103(a) as being unpatentable over Chen et al. (US Patent No. 6,602,775). Claim 8 was objected for informalities.

Claims 8 and 9 have been amended for clarification purposes. No new matter has been added to the application by the amendments made to the specification, claims and drawings. This Amendment is promptly filed to place the above-captioned case in condition for allowance. After entering the amendments, a notice of allowance is respectfully solicited.

#### Allowable subject matter

The Office Action mailed October 05, 2004, has indicated that claims 1-7 are allowed.

Applicant appreciates this indication of allowable subject matter.

#### Discussion for objections of claims

Claim 8 was objected for informalities.

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Claim 8 has been amended to correct the informalities. Withdrawal of this objection is respectfully requested.

**Discussion for 35 USC§102 and 103 rejections**

*Claims 8-10 and 12-13 were rejected under 35 USC§102(e) as being anticipated by Chen et al. (US Patent No. 6,602,775). Claims 11 and 14 were rejected under 35 USC§103(a) as being unpatentable over Chen et al. (US Patent No. 6,602,775).*

The Applicant has carefully considered the remarks set forth in the Office Action.

Claim 1 has been amended to provide more descriptions for clarification purposes and recites "forming a plurality of stair-like openings located above the bonding pads in the photoresist layers by a single exposure process". Claim 9 has been amended for clarification purposes.

As indicated by the Office Action, the prior art of record fails to teach or suggest, either alone or in combination, the steps of performing a single exposure process to the first and second photoresist layers to form a plurality of first openings in the first photoresist layer and a plurality of second openings in the second photoresist layer simultaneously.

Applicant respectfully asserts that the bumping process of the amended claim 8 is patentably distinct from the prior art method, especially the bumping process comprising forming a plurality of stair-like openings located above the bonding pads in the

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photoresist layers by a single exposure process. The reference Chen teaches two exposure processes with different lights (fig.3 and fig.4).

Accordingly, the reference Chen fails to teach or disclose all limitations as recited in the amended independent claim 8. Claims 9-10 and 12-13 depend from claim 8, and therefore are not anticipated by the reference Chen for the reasons noted above, as well as for the additional features recited therein. Therefore, reconsideration and withdrawal of these 102 rejections are respectfully requested.

Accordingly, it is respectfully submitted that claims 11 and 14 patentably distinguishes over the cited prior art, either alone or in combination, for at least the reasons stated above as well as for the additional features that these claims recite.

Withdrawal of these rejections under 35 USC 103(a) is respectfully requested.

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### CONCLUSION

In view of the foregoing, it is believed that all pending claims are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Date :

January 4, 2004

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